



## Material Content Data Sheet



<b>Sales Product Name</b>				IR38164MTRPBF		<b>Issued</b>		21. October 2018	
<b>MA#</b>				MA001711836					
<b>Package</b>				PG-IQFN-34-900		<b>Weight*</b>		118.33 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	3.873	3.27	3.27	32734	32734	
chip_2	inorganic material	silicon	7440-21-3	0.793	0.67	0.67	6698	6698	
chip_3	inorganic material	silicon	7440-21-3	0.278	0.24	0.24	2350	2350	
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		110		
	non noble metal	zinc	7440-66-6	0.052	0.04		441		
	non noble metal	iron	7439-89-6	1.043	0.88		8811		
	non noble metal	copper	7440-50-8	42.333	35.78	36.71	357755	367117	
wire	noble metal	gold	7440-57-5	0.493	0.42	0.42	4166	4166	
encapsulation	organic material	carbon black	1333-86-4	0.103	0.09		874		
	plastics	epoxy resin	-	5.327	4.50		45015		
	inorganic material	silicondioxide	60676-86-0	46.285	39.13	43.72	391151	437040	
leadfinish	noble metal	palladium	7440-05-3	0.001	0.00		12		
	noble metal	gold	7440-57-5	0.002	0.00		19		
	non noble metal	nickel	7440-02-0	0.041	0.03	0.03	345	376	
plating	noble metal	palladium	7440-05-3	0.001	0.00		12		
	noble metal	gold	7440-57-5	0.002	0.00		20		
	non noble metal	nickel	7440-02-0	0.042	0.04		356		
	noble metal	silver	7440-22-4	0.604	0.51	0.55	5103	5491	
solder	noble metal	silver	7440-22-4	0.132	0.11		1116		
	non noble metal	tin	7440-31-5	0.264	0.22		2232		
	non noble metal	lead	7439-92-1	4.887	4.13	4.46	41296	44644	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.004	0.00		30		
	non noble metal	zinc	7440-66-6	0.014	0.01		119		
	non noble metal	iron	7439-89-6	0.282	0.24		2385		
	non noble metal	copper	7440-50-8	11.460	9.68	9.93	96850	99384	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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